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Chemically amplified resist used in micro-engineering using excimer laser
- comprises alkali soluble resin, radiation sensitive, acid generator and
cpd. contg. nitrogen contg. basic gp

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EP 558280	A1	19930901	EP 93301340	A	19930223	199335 B
JP 5232706	A	19930910	JP 9273169	A	19920225	199341
US 5580695	A	19961203	US 9319871	A	19930219	199703
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JP 11223948	A	19990817	JP 9273169	A	19920225	199943
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Abstract (Basic): EP 558280 A

A novel chemically-amplified resist comprises: (a) a resin which is either alkali-soluble or contains an acid-dissociable gp. which becomes alkali-soluble upon dissociation; (b) a radiation-sensitive, acid-generating agent; (c) a cpd. contg. a N-contg. basic gp.; and (d) as opt. components one which controls the alkali solubility of the alkali-soluble resin and another which crosslinks this resin. When parts of the resist are irradiated, the acid-generating agent releases acid in the irradiated parts which catalyses a chemical reaction which varies the solubility of the resin and the opt. component so forming a pattern.

Pref., the resist comprises 100 pts.wt. resin, 0.001-10 pts.wt. N-contg. cpd. 1-70 pts.wt. acid generating agent, 5-150 pts.wt. opt. alkali-solubility controlling agent, and 5-95 pts.wt. crosslinker.

USE/ADVANTAGE - Can be used in micro-engineering using an excimer laser. It has high sensitivity and resolution and has good process stability

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